

A Low Power One-key Capacitor Touch Sensor

Features

- Sensitivity adjusted by the capacitance (0~50pF) outside
- Maximum response time

Slow scan mode: 160msFast scan mode: 48ms

- Push-pull output (AW93001STR/DSTR/DNR /HDNR /MDNR)
 - Active high/low selected by pin AHLB
- Open-drain output, active low (AW93001BSTR /CSTR/BDNR/GDNR/LDNR)
- Toggle output selected by pin TOG
- Low power consumption

Slow scan mode: 1.0μAFast scan mode: 3.2μA

- 2.4V~5.5V power supply
- Operation temperature range: -40°C~85°C
- Package
 - SOT23-6L
 - DFN 1.5mmx1.0mmx0.55mm-6L
 - > DFN 2.0mmx2.0mmx0.75mm-6L

General Description

AW93001 is a single channel capacitive touch controller with low power consumption and wide operation voltage range.

With the help of signal processing algorithms, the device is able to track slow environmental variations, and maintain high performance operation.

AW93001 is designed for replacing traditional mechanical button. It can be applied in many fields, such as consumer electronics, white goods and appliances, etc.

Applications

Wearable device, White goods and appliances Replacing traditional mechanical button

Typical Application Circuit

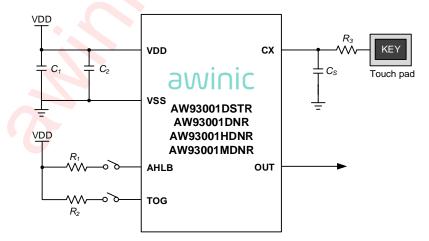


Figure 1 AW93001STR/DSTR/DNR/HDNR/MDNR Typical Application Circuit(push-pull output)



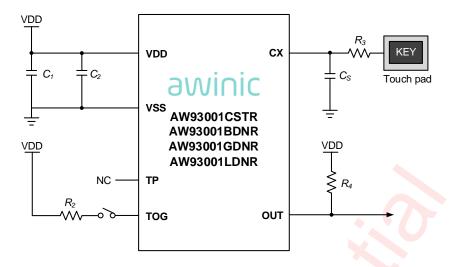
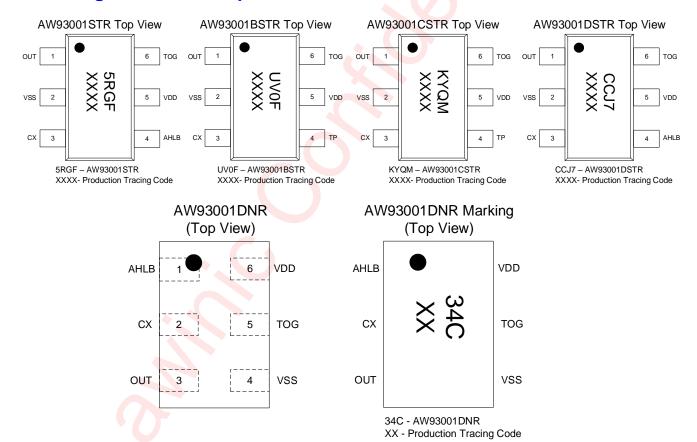


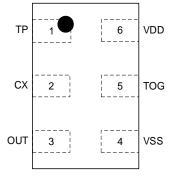
Figure 2 AW93001BSTR/CSTR/BDNR/GDNR/LDNR Typical Application Circuit(open-drain output)

Pin Configuration And Top Mark

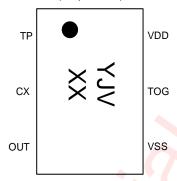






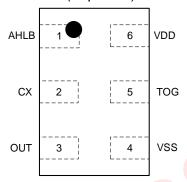


AW93001BDNR Marking (Top View)

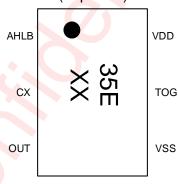


YJV - AW93001BDNR XX - Production Tracing Code

AW93001HDNR (Top View)

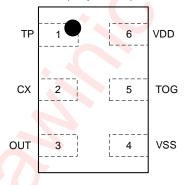


AW93001HDNR Marking (Top View)

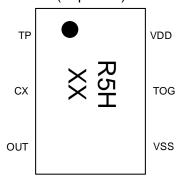


35E - AW93001HDNR XX - Production Tracing Code

AW93001GDNR (Top View)

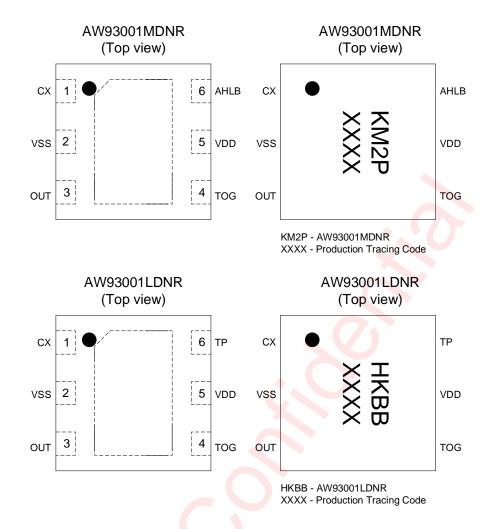


AW93001GDNR Marking (Top View)



R5H - AW93001GDNR XX - Production Tracing Code





Pin Definition

Table 1 AW93001STR/DSTR/DNR/HDNR/MDNR Pin Definition

		Pin No.		
NAME	AW93001 STR/DSTR	AW93001 DNR/HDNR	AW93001 MDNR	DESCRIPTION
OUT	1	3	3	Push-pull output
VSS	2	4	2	Ground
CX	3	2	1	Capacitive detector input
AHLB	4	1	6	Output active high or low selection, internal pull-down resistor of $50k\Omega$ Floating : Active high; Tied high: Active low
VDD	5	6	5	Power supply (2.4V~5.5V), requires decoupling capacitor
TOG	6	5	4	Output type option, internal pull-down resistor of $50k\Omega$ Floating : Direct output; Tied high: Toggle output



Table 2 AW93001BSTR/CSTR/BDNR/GDNR/LDNR Pin Definition

		Pin No.				
NAME	AW93001 BSTR/CSTR	AW93001 BDNR/GDNR	AW93001 LDNR	DESCRIPTION		
OUT	1	3	3	Open-drain output, requires pull-up resistor		
VSS	2	4	2	Ground		
CX	3	2	1	Capacitive detector input		
TP	4	1	6	Test pin, typically floating		
VDD	5	6	5	Power supply (2.4V~5.5V), requires decoupling capacitor		
TOG	6	5	4	Output type option, internal pull-down resistor of 50kΩ Floating : Direct output; Tied high: Toggle output		

Device Comparison

Table 3 Device Comparison

Device	Pookogo	Scan	mode	МОТ	Output Mada
Device	Package	Fast scan	Slow scan	MOI	Output Mode
AW93001STR	SOT23-6L	√	1		Push-pull
AW93001BSTR	SOT23-6L	√	√		Open-drain
AW93001DNR	DFN1510-6L	√	1		Push-pull
AW93001BDNR	DFN1510-6L	√	1	160	Open-drain
AW93001HDNR	DFN1510-6L	1		16s	Push-pull
AW93001GDNR	DFN1510-6L	1			Open-drain
AW93001MDNR	DFN2x2-6L	1			Push-pull
AW93001LDNR	DFN2x2-6L	√			Open-drain
AW93001CSTR	SOT23-6L	1		1000	Open-drain
AW93001DSTR	SOT23-6L	√		100s	Push-pull



Functional Block Diagram

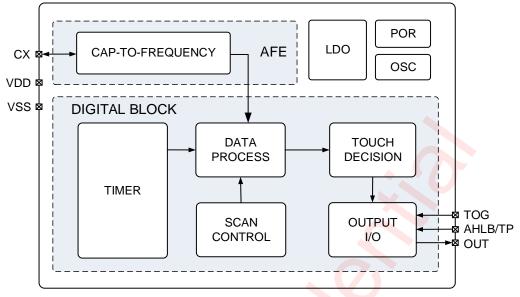


Figure 3 Functional Block Diagram

Ordering Information

Part Number	Temperature	Package	Marking	Moisture Sensitivity Level	Environmental Information	Delivery Form	
AW93001STR	-40°C~85°C	SOT23-6L	5RGF	MSL3	ROHS+HF	3000 units/ Tape and Reel	
AW93001BSTR	-40°C~85°C	SOT23-6L	UV0F	MSL3	ROHS+HF	3000 units/ Tape and Reel	
AW93001CSTR	-40°C~85°C	SOT23-6L	KYQM	MSL3	ROHS+HF	3000 units/ Tape and Reel	
AW93001DSTR	-40°C~85°C	SOT23-6L	CCJ7	MSL3	ROHS+HF	3000 units/ Tape and Reel	
AW93001DNR	-40°C~85°C	DFN 1.5mmx1.0mm-6L	34C	MSL1	ROHS+HF	4500 units/ Tape and Reel	
AW93001BDNR	-40°C~85°C	DFN 1.5mmx1.0mm-6L	YJV	MSL1	ROHS+HF	4500 units/ Tape and Reel	
AW93001HDNR	-40°C~85°C	DFN 1.5mmx1.0mm-6L	35E	MSL1	ROHS+HF	4500 units/ Tape and Reel	
AW93001GDNR	-40°C~85°C	~85°C DFN 1.5mmx1.0mm-6L R5H		MSL1	ROHS+HF	4500 units/ Tape and Reel	
AW93001MDNR	W93001MDNR -40°C~85°C DFN 2.0mmx2.0mm-6L		KM2P	MSL1	ROHS+HF	3000 units/ Tape and Reel	
AW93001LDNR	03001LDNR -40°C~85°C DFN 2.0mmx2.0mm-6L		HKBB	MSL1	ROHS+HF	3000 units/ Tape and Reel	

Absolute Maximum Ratings(NOTE1)



PARAMETER	PARAMETERS					
Supply voltage rang	Supply voltage range VDD					
Input voltage range	CX, TP, AHLB, TOG	-0.3V to 6.0V				
Output voltage range	OUT	-0.3V to 6.0V				
Operating free-air tempe	rature range	-40°C to 85°C				
Maximum operating junction t	emperature T _{JMAX}	150°C				
Storage temperatur	e T _{STG}	-65°C to 150°C				
Lead temperature (soldering	ng 10 seconds)	260°C				
E	SD(Including CDM HBM) ^{(N}	OTE 2)				
НВМ		±6kV				
CDM	CDM					
	Latch-Up					
Test condition: JES	Test condition: JESD78E					

NOTE1: Conditions out of those ranges listed in "absolute maximum ratings" may cause permanent damages to the device. Exposure to absolute-maximum-rated conditions for prolonged periods may affect device reliability.

NOTE2: The human body model is a 100pF capacitor discharged through a 1.5k Ω resistor into each pin. Test method: ANSI/ESDA/JEDEC JS-001-2017(HBM), ANSI/ESDA/JEDEC JS-002-2018(CDM).

Electrical Characteristics

Note: Typical values are given for $T_A = +25^{\circ}C$, VDD=3.0V unless otherwise specified.

	PARAMETER	TEST CONDITION	MIN	TYP	MAX	UNIT
VDD	Operation voltage	-	2.4	3.0	5.5	V
IsL	Current in slow scan mode	Cs=20pF, scan period=128ms	-	1.0	-	μΑ
I _{FS}	Current in fast scan mode	Cs=20pF, scan period=16ms	-	3.2	-	μА
VIH	Input high level	Pin AHLB, TOG	1.4	-	-	V
V _{IL}	Input low level	Pin AHLB, TOG	-	-	0.4	V
I _{OH}	Output high current	VOH≥VDD-0.4V	-	-	-4	mA
loL	Output low current	VOL≤0.4V	8	-	-	mA
R _{PD}	Input pin pull-down resistor	Pin TOG, AHLB	-	50	-	kΩ
TRESP	Response time(NOTE 3)	Fast scan mode	34	-	48	ms
I KESP	Nesponse une	Slow scan mode	34	-	160	ms

NOTE3: It has an error of ± 10% according to the mass production test data.



Detailed Functional Description

Initialization

After power-on, the chip executes initialization process automatically, it lasts for about 500ms. During initialization, touch decision does not work, and no touch status can be reported.

Scan Mode

The AW93001STR/BSTR/DNR/BDNR have two scan modes, fast scan mode and slow scan mode, In fast scan mode, the scan period is about 16ms, and the maximum response time is about 48ms. In slow scan mode, the scan period is about 128ms with lower power consumption, and the maximum response time is about 160ms. For power saving, the device automatically switches scan mode between fast and slow mode according to touch detection status. After power-on, the device enters fast scan mode directly. In fast scan mode, if there is no touch detected for 8s continuously, the device switches to slow scan mode. In slow scan mode, if touch is detected, the device returns to fast scan mode at once.

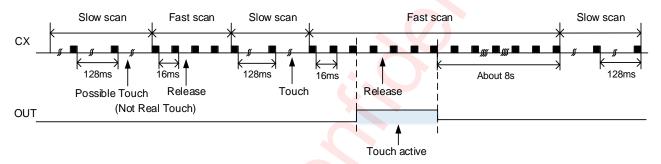


Figure 4 Two Scan Modes

The AW93001CSTR/DSTR/HDNR/GDNR/MDNR/LDNR only has fast scan mode. In fast scan mode, the scan period is about 16ms, and the maximum response time is about 48ms. After power-on, the device enters fast scan mode directly and keeps it all the time.

Output Mode

For AW93001STR/DNR/HDNR/MDNR, pin OUT is a push-pull output, and the output mode depends on the initial power-on states of pin AHLB and pin TOG. Pin TOG selects direct output or toggle output, and pin AHLB selects active high or active low.

Table 4 AW93001STR/DSTR/DNR/HDNR/MDNR Output Mode

Pin TOG	Pin AHLB	Pin OUT's output mode			
Floating Floating		Direct output, active high			
Floating	Tied high	Direct output, active low			
Tied high	Floating	Toggle output, initial state is low			
Tied high	Tied high	Toggle output, initial state is high			

For AW93001BSTR/CSTR/BDNR/GDNR/LDNR, pin OUT is an open-drain output, and the output mode only depends on the initial power-on state of pin TOG.



Table 5 AW93001BSTR/CSTR/BDNR/GDNR/LDNR Output Mode

Pin TOG	Pin OUT's output mode			
Floating	Direct output, active low			
Tied high	Toggle output, initial state is high-Z			

When pin AHLB or pin TOG is tied high, the internal pull-down function of these pin is closed, so no additional power consumption will be generated.

Maximum Key-on Duration Time

In order to prevent the false touch detection caused by objects covering the touch pad, the chip sets maximum key-on duration time. For AW93001STR/BSTR/DNR/BDNR/HDNR/GDNR/MDNR/LDNR, if the devices' touch status last over 16s, it will be released until a new touch action. For AW93001CSTR/DSTR, if the devices' touch status last over 100s, it will be released until a new touch action.

Application Information

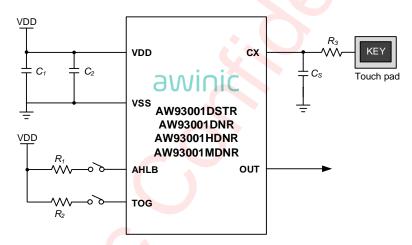


Figure 5 AW93001STR/DNR/HDNR/MDNR Typical Application Circuit(push-pull output)

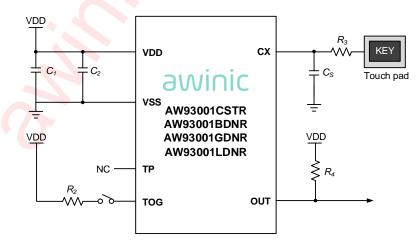


Figure 6 AW93001BSTR/CSTR/BDNR/GDNR/LDNR Typical Application Circuit(open-drain output)

To obtain the optimal performance, the capacitive touch controller's application circuit should be considered carefully. Here are some guidelines:

- 1. The chip should be supplied by stable power, otherwise it may cause abnormal sensitivity or false detection.
- 2. Add a resistor R₃ between C_S and Touch pad to improve ESD protection and reduce EMI.
- 3. Sensitivity can be adjusted by C_S. The smaller the C_S, the higher the sensitivity, the higher the power consumption. The range of C_S is 0~50pF. It is suggested to use temperature insensitive capacitors to adjust the sensitivity, such as NP0 capacitors.
- 4. Sensitivity can be adjusted by the electrode size. Using a larger electrode size can increase sensitivity, but the electrode size must be used in the effective scope.
- 5. Sensitivity can be adjusted by the panel thickness. Using a thinner panel can increase sensitivity, but the panel thickness must be used in the effective scope.

Recommended Components List

Component	Name	Description	Тур.	Unit
	C ₁	-	1	μF
С	C ₂	-	0.1	μF
	Cs	5% resolution Low temperature coefficient	-	pF
	R ₁ , R ₂	5% resolution	4.7	kΩ
R	R ₃	R ₃ 5% resolution		kΩ
	R ₄	5% resolution	100	kΩ

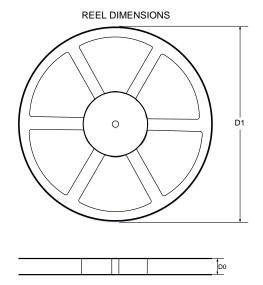
PCB Layout Consideration

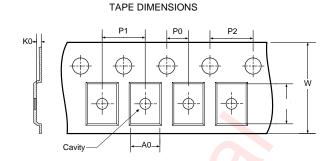
To obtain the optimal performance, PCB layout should be considered carefully. Here are some guidelines:

- 1. The connections between the capacitors (C_1, C_2) and the IC as short as possible, to reduce noise and EMI.
- 2. The distance from the touch pad to the pin CX as short as possible, and the signal trace as thin as possible.
- 3. The IC and sensor traces surrounded by ground, both top and bottom layers filled with ground plane.
- 4. The sensor and traces away from mic, earphone line, because capacitive sensor will disturb audio line.
- 5. The sensor and traces away from interferences, such as communication lines.
- 6. The material of panel covering the PCB cannot contain metal or electric element, and the surface coating is the same.



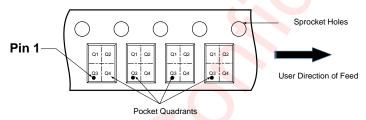
Tape And Reel Information





- A0: Dimension designed to accommodate the component width
- B0: Dimension designed to accommodate the component length
- K0: Dimension designed to accommodate the component thickness
- W: Overall width of the carrier tape
- P0: Pitch between successive cavity centers and sprocket hole
 P1: Pitch between successive cavity centers
- P2: Pitch between sprocket hole
- D0: Reel Width

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



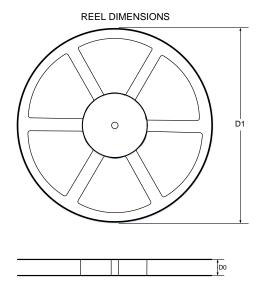
Note: The above picture is for reference only. Please refer to the value in the table below for the actual size

DIMENSIONS AND PIN1 ORIENTATION

D1	D0	A0	B0	K0	P0	P1	P2	W	Pin1 Quadrant
(mm)									
178	8.4	3.3	3.2	1.4	2	4	4	8	Q3

All dimensions are nominal

AW93001STR/BSTR/CSTR/DSTR Tape And Reel Information

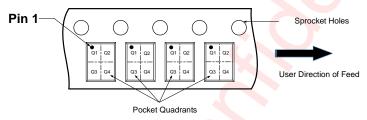


-A0-Cavity

TAPE DIMENSIONS

- A0: Dimension designed to accommodate the component width B0: Dimension designed to accommodate the component length
- K0: Dimension designed to accommodate the component thickness
- W: Overall width of the carrier tape
- P0: Pitch between successive cavity centers and sprocket hole P1: Pitch between successive cavity centers
- P2: Pitch between sprocket hole
- D1: Reel Diameter
- D0: Reel Width

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Note: The above picture is for reference only. Please refer to the value in the table below for the actual size

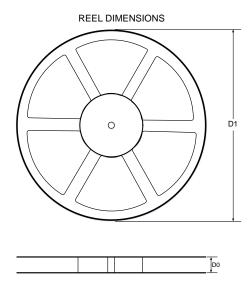
DIMENSIONS AND PIN1 ORIENTATION

D1	D0	A0	В0	K0	P0	P1	P2	W	Pin1 Quadrant
(mm)	Fili Quadrant								
178	8.4	1.12	1.72	0.7	2	4	4	8	Q1

All dimensions are nominal

AW93001DNR/BDNR/HDNR/GDNR Tape And Reel Information

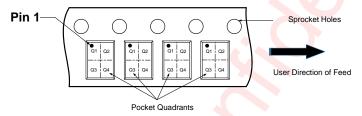




TAPE DIMENSIONS KO+1 -A0-Cavity

- A0: Dimension designed to accommodate the component width B0: Dimension designed to accommodate the component length
- K0: Dimension designed to accommodate the component thickness
- W: Overall width of the carrier tape
- P0: Pitch between successive cavity centers and sprocket hole
- P1: Pitch between successive cavity centers
- P2: Pitch between sprocket hole
- D1: Reel Diameter D0: Reel Width

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Note: The above picture is for reference only. Please refer to the value in the table below for the actual size

DIMENSIONS AND PIN1 ORIENTATION

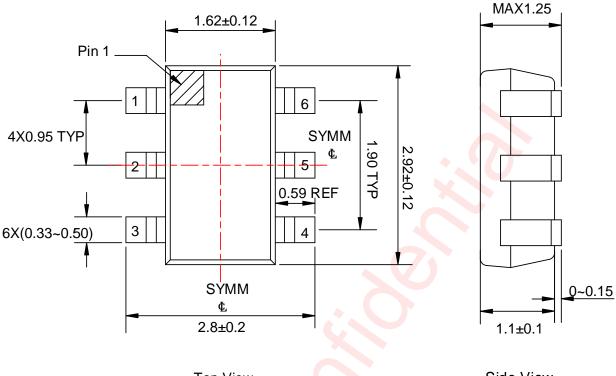
D1	D0	A0	B0	K0	P0	P1	P2	W	Bin1 Oundrant	
(mm)	Pin1 Quadrant									
178	8.4	2.3	2.3	1	2	4	4	8	Q1	

All dimensions are nominal

AW93001MDNR/LDNR Tape And Reel Information

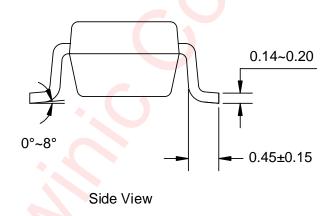


Package Description



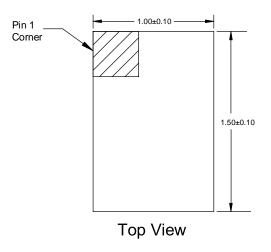
Top View

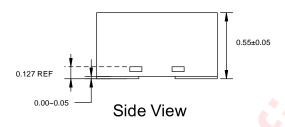
Side View

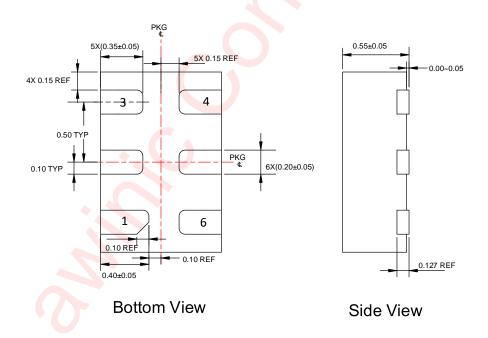


Unit: mm

AW93001STR/BSTR/CSTR/DSTR Package Description



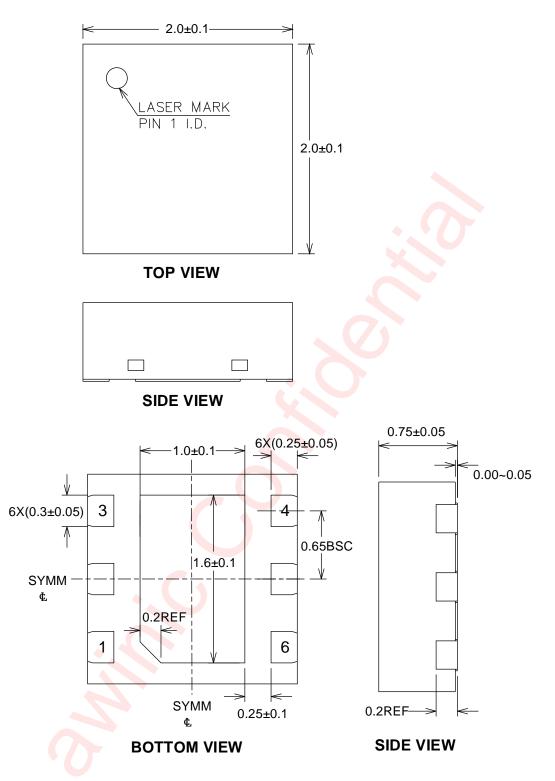




Unit: mm

AW93001DNR/BDNR/HDNR/GDNR Package Description



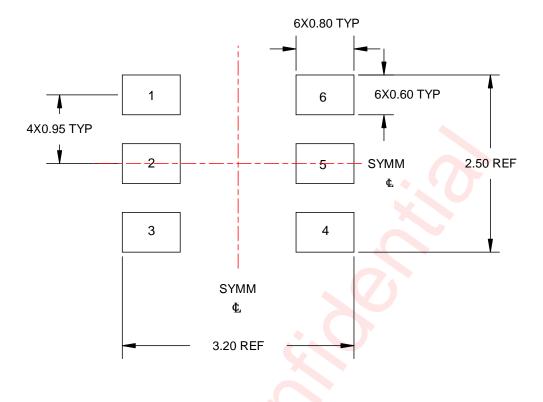


Unit:mm

AW93001MDNR/LDNR Package Description



Land Pattern Data

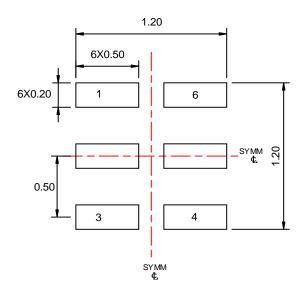


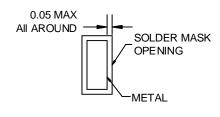


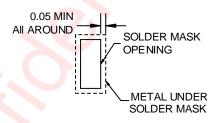
Unit: mm

AW93001STR/BSTR/CSTR/DSTR Land Pattern Data









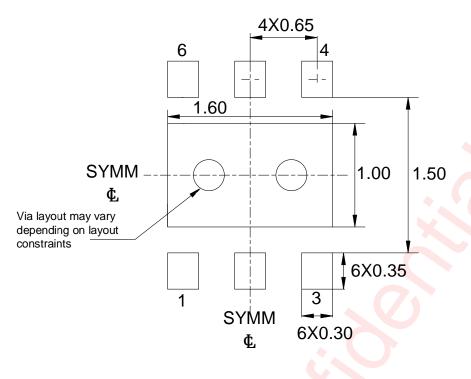
NON SOLDER MASK DEFINED

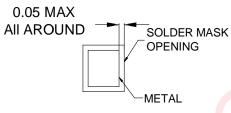
SOLDER MASK DEFINED

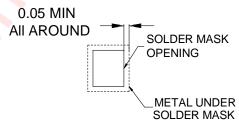
Unit: mm

AW93001DNR/BDNR/HDNR/GDNR Land Pattern Data









NON SOLDER MASK DEFINED

SOLDER MASK DEFINED

Unit:mm

AW93001MDNR/LDNR Land Pattern Data



Revision History

Version	Date	Change Record
V1.0	Feb.2021	Officially released
V1.1	Feb.2021	Merge the AW93001STR/BSTR/DNR/BDNR's datasheet; Add a resistor between C _S and Touch pad in Typical Application Circuit
V1.2	May.2021	Update Ordering Information
V1.3	Jul.2021	Add the chip,AW93001HDNR's information
V1.4	Jul.2021	Correct the AW93001HDNR's tracing code, update the package DFN1510-6's POD information
V1.5	Jul.2021	Add the chip,AW93001GDNR's information, update the Device Comparison table
V1.6	Nov.2021	Add the chip,AW93001MDNR/LDNR's information, update the Device Comparison table; Correct the R3 resistor value in Recommended Components List.
V1.7	Dec.2021	Update Ordering Information
V1.8	Mar.2022	Update Device Comparison, correct the AW93001STR/BSTR/DNR/BDNR's MOT value, update Functional Block Diagram.
V1.9	May.2022	Add the chip, AW93001CSTR's information, update the Device Comparison table
V2.0	Sep.2022	Update the Absolute Maximum Ratings, correct the maximum voltage range; Update the AW93001STR/BSTR/CSTR Tape And Reel Information
V2.1	Oct.2022	Add the chip,AW93001DSTR's information, update the Device information
V2.2	Jul.2023	Add the minimum response time in the table of Electrical Characteristics (P7).

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